General Description

The MAX532 is a complete, dual, serial-input, 12-bit multiplying digital-to-analog converter (MDAC) with output amplifiers. No external user trims are required to achieve full specified performance. The MAX532's 3-wire serial interface minimizes the number of package pins, so it uses less board space than parallel-interface parts. The interface is SPI™, QSPI™ and Microwire™ compatible. A serial output, DOUT, allows cascading of two or more MAX532s and read-back of the data written to the device.

The device's serial interface minimizes digital-noise feedthrough from its logic pins to its analog outputs. Serial interfacing also simplifies opto-coupler-isolated or transformer-isolated applications.

The MAX532 is specified with $\pm 12V$ to $\pm 15V$ power supplies. All logic inputs are TTL and CMOS compatible. It comes in space-saving 16-pin DIP and wide SO packages.

Applications

Automatic Test Equipment

Arbitrary Waveform Generators

Programmable-Gain Amplifiers

Motion Control Systems

Servo Controls

Functional Diagram



- Features
 Two 12-Bit MDACs with Output Amplifiers
- _____
- Fast, 6MHz 3-Wire Interface
- SPI, QSPI, and Microwire Compatible
- ±12V Output Swing
- ±10mA Output Current
- 2.5µs Settling Time to ±1/2LSB
- Guaranteed Monotonic Over Temperature
- Low Integral Nonlinearity: ±1/2LSB Max
- + Low Gain Tempco: 2ppm/°C
- Operates from ±12V to ±15V Supplies
- Power-On Reset
- Available in 16-Pin DIP and Wide SO Packages

Ordering Information

PART	TEMP. RANGE	PIN-PACKAGE	ERROR (LSBs)
MAX532ACPE	0°C to +70°C	16 Plastic DIP	±1/2
MAX532BCPE	0°C to +70°C	16 Plastic DIP	±1
MAX532ACWE	0°C to +70°C	16 Wide SO	±1/2
MAX532BCWE	$0^{\circ}C$ to $+70^{\circ}C$	16 Wide SO	±1
MAX532BC/D	0°C to +70°C	Dice*	+1

Ordering Information continued on last page.

* Contact factory for dice specifications.



_Pin Configuration

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Maxim Integrated Products

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Call toll free 1-800-998-8800 for free samples or literature.

MAX532

ABSOLUTE MAXIMUM RATINGS

Pin Voltages
V _{DD} to DGND, AGNDA, AGNDB0.3V to +17V
V _{SS} to DGND, AGNDA, AGNDB (Note 1)+0.3V to -17V
VREFA, VREFB(V _{SS} - 0.3V) to (V _{DD} + 0.3V)
AGNDA, AGNDB(DGND - 0.3V) to (V _{DD} + 0.3V)
VOUTA, VOUTB(V _{SS} - 0.3V) to (V _{DD} + 0.3V)
RFBA, RFBB(V _{SS} - 0.3V) to (V _{DD} + 0.3V)
SCLK, DIN, DOUT, LDAC, CS(DGND - 0.3V) to (V _{DD} + 0.3V)
DOUT Sink Current
Continuous Power Dissipation ($T_A = +70^{\circ}C$)
Plastic DIP (derate 10.53mW/°C above +70°C)842mW
Wide SO (derate 9.52mW/°C above +70°C)762mW
CERDIP (derate 10.00mW/°C above +70°C)800mW

Operating Temperature Ranges:

operating remperature ranges.	
MAX532_C	0°C to +70°C
MAX532_E	40°C to +85°C
MAX532_MJE	55°C to +125°C
Junction Temperatures:	
MAX532_C, E	+150°C
MAX532_MJE	+175°C
Storage Temperature Range	65°C to +160°C
Lead Temperature (soldering, 10sec)	+300°C

Note 1: If V_{SS} is open-circuited with V_{DD} and either AGND applied, the V_{SS} pin will float positive, exceeding the Absolute Maximum Ratings. A Schottky diode connected between V_{SS} and GND ensures the maximum ratings will not be exceeded.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

 $(V_{DD}$ = 11.4V to 16.5V, V_{SS} = -11.4V to -16.5V, AGNDA = AGNDB = DGND = 0V, VREFA and VREFB = +10V, R_L = 2k Ω , C_L = 100pF, VOUT_ connected to RFB_, T_A = T_{MIN} to T_{MAX} , unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS			TYP	MAX	UNITS
STATIC PERFORMANCE	(Note 1)						
Resolution				12			Bits
Relative Accuracy	INI		MAX532A			±1/2	L SB
Relative Accuracy			MAX532B			±1	- LSB
Differential Nonlinearity		Guaranteed monotonic				±1	LSB
			T _A = +25°C, MAX532_			±2	
Zero-Code Offset Error		DAC latch loaded with all 0s	$T_A = T_{MIN}$ to T_{MAX} , MAX532A			±3	mV
		with dir 05	$T_A = T_{MIN}$ to T_{MAX} , MAX532B			±4	1
Zero-Code Offset Temperature Coefficient		DAC latch loaded with all 0s			±5		µV/°C
Gain Error		$T_A = +25$ °C, DAC latch loaded with all 1s	MAX532A			±2	LSB
			MAX532B			±5	
		TA - TMIN TO TMAX, DAC	MAX532A			±4	
			MAX532B			±7	
Gain-Error Temperature Coefficient					±2		ppm/°C of FSR
REFERENCE INPUTS (V	REFA, VRE	FB)					-
VREFA, VREFB Input Resistance				8	10	13	kΩ
VREFA, VREFB Input Resistance Matching					±0.5	±3.0	%

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{DD} = 11.4V \text{ to } 16.5V, V_{SS} = -11.4V \text{ to } -16.5V, \text{AGNDA} = \text{AGNDB} = \text{DGND} = 0V, \text{VREFA and VREFB} = +10V, \text{R}_L = 2k\Omega, \text{C}_L = 100\text{pF}, \text{VOUT_connected to RFB_, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.}$

PARAMETER	SYMBOL	со	NDITIONS	MIN	TYP	MAX	UNITS	
DIGITAL INPUTS (SCLK,	DIN, LDAC,	CS)						
Input High Voltage	V _{INH}			2.4			V	
Input Low Voltage	V _{INL}					0.8	V	
Input Current		Digital inputs at 0V or V	DD			±1	μA	
Input Capacitance (Note 2)						8	рF	
DIGITAL OUTPUT (DOUT)	(Note 3)			1				
	Max	I _{SINK} = 5mA			0.08	0.4		
Output Voltage Low	Vol	I _{SINK} = 16mA			0.2		- V	
Output High Leakage	I _{LKG}	$V_{DOUT} = 0V \text{ to } V_{DD}$				±10	μA	
Output High Capacitance (Note 2)	C _{OUT}					15	pF	
ANALOG OUTPUTS (VOU	ITA, VOUTI	3)						
DC Output Impedance					0.2		Ω	
Short-Circuit Current		VOUTA, VOUTB connec	cted to AGNDA, AGNDB		20		mA	
Output Voltage Swing				(V _{DD} - 2 to (V _{SS} + 2			v	
POWER REQUIREMENTS	i							
Positive Supply Voltage	V _{DD}			11.4		16.5	V	
Negative Supply Voltage	V _{SS}			-11.4		-16.5	V	
Power-Supply Rejection PSR		Δ Full scale/ Δ V _{DD} , V _{DD} = 11.4V to 16.5V, VREF = -8.9V, DAC latches loaded with all 1s				±0.035	LSB/%	
		$\Delta Full scale/\Delta V_{SS},$ V_{SS} = -11.4V to -16.5V, VREF = 8.9V, DAC latches loaded with all 1s				±0.035		
Positive Supply Current	I _{DD}	Output unloaded			5	10	mA	
Negative Supply Current	I _{SS}	Output unloaded			4	6	mA	
AC CHARACTERISTICS								
Voltage-Output Settling Time			Settling time to within 1/2 LSB of final DAC value; DAC latch alternately loaded with all 0s and all 1s		2.5		μs	
Slew Rate					8		V/µs	
Digital-to-Analog Glitch Impulse		DAC latch alternately loaded with 01111 and 10000			60		nV-s	
Channel-to-Channel		VREFA to VOUTB	VREFA = 20V _{p-p} 10kHz sine wave; DAC latches loaded with all 0s		-100		dB	
Isolation		VREFB to VOUTA	VREFB = 20V _{p-p} 10kHz sine wave; DAC latches loaded with all 0s		-100			

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ELECTRICAL CHARACTERISTICS (continued)

 $(V_{DD} = 11.4V \text{ to } 16.5V, V_{SS} = -11.4V \text{ to } -16.5V, \text{AGNDA} = \text{AGNDB} = \text{DGND} = 0V, \text{VREFA and VREFB} = +10V, \text{R}_L = 2k\Omega, \text{C}_L = 100\text{pF}, \text{VOUT}_ \text{connected to RFB}, \text{T}_A = \text{T}_{\text{MIN}} \text{ to } \text{T}_{\text{MAX}}$, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN T	ГҮР	MAX	UNITS
Multiplying Feedthrough Error		$\label{eq:VREF} VREF = 20V_{p\cdot p} \ 10 \text{kHz sine wave;} \\ \text{DAC latch loaded with all 0s} \ -77$			dB	
Unity-Gain Small-Signal Bandwidth		VREF = 100mV _{p-p} sine wave; DAC latch loaded with all 1s		MHz		
Full-Power Bandwidth		VREF = 20Vp-p sine wave; DAC latch loaded with all 1s125		kHz		
Total Harmonic Distortion	THD	VREF = 6V _{RMS} , 1kHz sine wave; DAC latch loaded with all 1s -90		dB		
Digital Feedthrough		\overline{CS} = 1; transitions on SCLK, \overline{LDAC} , DIN 1.1		nV-s		
Digital Crosstalk		DACA code all 1s, DACB code transition from all 0s to all 1s 10		nV-s		
Output Noise Voltage		0.1Hz to 10Hz 2 H		μV _{RMS}		

Note 1: Static performance tested at V_{DD} = +15V, V_{SS} = -15V. Performance over supplies guaranteed by PSR test.
 Note 2: Guaranteed by design. Not subject to production testing.
 Note 3: Open-drain output.

TIMING CHARACTERISTICS

 $(V_{DD} = 11.4V \text{ to } 16.5V, V_{SS} = -11.4V \text{ to } -16.5V, AGNDA = AGNDB = DGND = 0V)$ (Notes 4, 5)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
SCLK Clock Frequency	fclk				6.25	MHz
SCLK Pulse Width High	t _{CH}		80			ns
SCLK Pulse Width Low	t _{CL}		80			ns
DIN to SCLK Rise Setup Time	t _{DS}		50			ns
DIN to SCLK Rise Hold Time	t _{DH}		0			ns
CS Fall to SCLK Rise Setup Time	t _{CSS0}		50			ns
CS Rise to SCLK Rise Setup Time	t _{CSS1}		50			ns
SCLK Fall to CS Fall Hold Time	t _{CSH0}		5			ns
SCLK Rise to CS Rise Hold Time	tCSH1		80			ns
CS Pulse Width High	t _{CSW}		120			ns
SCLK Fall to DOUT Valid (Note 6)	t _{DO}	C_L = 20pF, $R_{PULL-UP}$ = 1k Ω to 5V	0		200	ns
CS Fall to DOUT Enable (Note 7)	t _{DV}	C_L = 20pF, $R_{PULL-UP}$ = 1k Ω to 5V			100	ns
CS Rise to DOUT Disable (Note 7)	t _{TR}	$C_L = 20 pF$, $R_{PULL-UP} = 1 k\Omega$ to 5V			60	ns
LDAC Pulse Width Low	t _{LDAC}		60			ns
CS Rise to LDAC Fall Setup Time	t _{LDACS}		100			ns

Note 4: All input signals are specified with $t_R = t_F \le 5ns$. Logic input swing is 0V to 5V.

Note 5: See Figure 1.

Note 6: Timing is for SCLK fall to DOUT fall to 0.8V, or for SCLK fall to DOUT rise to 2.4V. Additional time must be added for any larger passive RC pull-up delay.
 Note 7: DOUT enable: DOUT falls to 4.5V from 5.0V. DOUT disable: DOUT rises to 0.5V from 0V.



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MAX532



V_{REFA} = ±100mV SQUARE WAVE



A = VOUTA, 5V/div TIMEBASE = 2μ s/div VREFA = $\pm 10V$ SQUARE WAVE

Pin Description

ΜΙΧΙΜ

PIN	NAME	FUNCTION
1	RFBA	Feedback Resistor for DACA
2	VREFA	Reference Input for DACA
3	VOUTA	Voltage Output for DACA
4	AGNDA	Analog Ground for DACA
5	AGNDB	Analog Ground for DACB
6	VOUTB	Voltage Output for DACB
7	VREFB	Reference Input for DACB
8	RFBB	Feedback Resistor for DACB
9	V _{SS}	Negative Supply Voltage
10	DGND	Digital Ground
11	SCLK	Serial Clock Input
12	DOUT	Serial Data Output. Open-drain N-channel MOSFET output: requires external pull-up resis- tor. Data on DOUT changes on the falling edge of SCLK. Serial output data is delayed 24 clock cycles from DIN.
13	DIN	Serial Data Input. CMOS- and TTL-compatible input. Data is clocked into DIN on the rising edge of SCLK. CS must be low for data to be clocked in.
14	CS	Chip-Select Input, active low. Data is shifted in and out when \overline{CS} is low. DAC latches are updated when \overline{CS} is high and \overline{LDAC} is low.
15	LDAC	Asynchronous Load DAC Input, active low. DAC latches are updated when CS is high and LDAC is low.
16	V _{DD}	Positive Supply Voltage



Figure 1. Timing Diagram



Figure 2. 3-Wire Interface Timing Diagram ($\overline{LDAC} = DGND$)



Figure 3. 4-Wire Inferface Timing Diagam

ΜΛΧΙΜ



Figure 4. Connections for Microwire

Detailed Description

Digital Interface

The MAX532 is Microwire and SPI compatible (Figures 4 and 5). Both DACs are programmed by writing three 8-bit words (see Figures 2 and 3, and the *Functional Diagram*). Serial data is clocked into the data registers MSB first, with DACB information preceding DACA information. Data is clocked in on the rising edge of SCLK while \overline{CS} is low. With \overline{CS} high, data can not be clocked into DIN, and DOUT is high impedance. SCLK can be driven at rates up to 6.25MHz.

The MAX532 uses either a 3-wire or a 4-wire serial interface. Three wires may be used (\overline{CS} , DIN, SCLK) by tying \overline{LDAC} low. With \overline{LDAC} low, the DACs are updated simultaneously when \overline{CS} goes high (see Figure 2 and the *Functional Diagram*). The 3-wire interface may be used if the MAX532 is used alone, or if two or more MAX532s are cascaded (DOUT of one device tied to DIN of the other) (Figure 6).

The 4-wire interface (**LDAC**, **CS**, DIN, SCLK) is required if several serial devices are tied to the same data line, and it is desirable to update them simultaneously (Figure 7). With the 4-wire interface, the DACs are updated when **LDAC** goes low (see Figure 3 and the *Functional Diagram*).

A serial output, DOUT, allows cascading of two or more MAX532s and allows read-back of the data written to

Dual, Serial-Input, Voltage-Output, 12-Bit MDAC



Figure 5. Connections for SPI

the device's 24-bit shift register. The data at DOUT is delayed 24 clock cycles from the data at DIN (see Figures 2 and 3, and the *Functional Diagram*). DOUT is an open-drain N-channel MOSFET that requires an external pull-up resistor (typically 1k Ω if pulled up to +5V, and 3k Ω if pulled up to +12V or +15V). Logic levels are guaranteed with sink currents up to 5mA (see *Electrical Characteristics*). Output data changes on the falling edge of SCLK when **CS** is low. If **CS** is high, DOUT is three-state (high-impedance).

Daisy-Chaining Devices

Any number of MAX532s can be daisy-chained by connecting the DOUT pin of one device (with a pull-up resistor) to the DIN pin of the following device in the chain (Figure 6).

When daisy-chaining devices, t_{CSS0} (\overline{CS} low to SCLK high), must be the greater of $t_{DV} + t_{DS}$ or $t_{DS} + (t_{RC} + t_{TR} - t_{CS})$, where t_{CSW} is the \overline{CS} pulse width used in the system and the term ($t_{RC} + t_{TR} - t_{CSW}$) accounts for the time spent charging the DOUT capacitance with the external pull-up resistor. So, for $t_{RC} < 250$ ns, t_{CSS0} is simply $t_{DV} + t_{DS}$. Calculate t_{RC} using the following equation:

 $t_{RC} = R_P \times C \times \ln (V_{PULL-UP}/(V_{PULL-UP} - 2.4V))$

where V_{PULL-UP} is the voltage that the pull-up resistor is connected to, R_P is the value of the pull-up resistor, and C is the capacitance at DOUT. Values of t_{RC} are given in Table 1.

MAX532



Figure 6. Daisy-chained or individual MAX532s are simultaneously updated by bringing \overline{CS} high when using the 3-wire interface ($\overline{LDAC} = DGND$).



Figure 7. Multiple devices sharing a common DIN line may be simultaneously updated by bringing **LDAC** low. CS1, CS2, CS3, . . ., are driven separately, thus controlling which data are written to devices 1, 2, 3,

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VPULL-UP (V)	C (pF)	R_P (k Ω)	t _{RC} (ns)
4.5	20	1	15
4.5	35	1	27
4.5	50	1	38
4.5	100	1	76
4.5	150	1	114
11.4	20	3	14
11.4	35	3	25
11.4	50	3	35
11.4	100	3	71
11.4	150	3	106
13.5	20	3	12
13.5	35	3	21
13.5	50	3	29
13.5	100	3	59
13.5	150	3	88

Table 1. t_{RC} Delay Times

With the values of t_{RC} given in Table 1, t_{CSS0} is always given by t_{DV} + $t_{DS}.$ For different values of R or C, t_{RC} must be calculated to determine $t_{CSS0}.$

Additionally, the maximum clock frequency is limited to

$$f_{CLK}(max) = \frac{1}{2 x (t_{DO} + t_{RC} - 15ns + t_{DS})}$$

For example, with t_{RC} = 15ns (5V ±10% supply with 1k Ω pull-up), the maximum clock frequency is 2MHz.

Digital-to-Analog Section

MAX532

Figure 8 shows a simplified circuit diagram for one of the DACs and the output amplifier.

A segmented scheme is used to improve linearity, whereby the two MSBs of the 12-bit data word are decoded to drive the three switches, SA, SB, and SC. The remaining ten bits drive the switches S0 through S9 in a standard R-2R ladder configuration.

Each of the switches, SA, SB, and SC, steers 1/4 of the total reference current with the remaining 1/4 passing through the R-2R section.

The output amplifier and feedback resistor perform the current-to-voltage conversion, giving the following:

VOUT_ = -D x VREF_,

where $_$ denotes A or B, and D is the fractional representation of the digital word. (D can be set from 0 to 4095/4096.)



Figure 9. Unipolar Binary Operation



Figure 8. Simplified D/A Circuit Diagram



Output Amplifiers

Voltage-Output, 12-Bit MDAC

The output amplifiers are stable with any combination of resistive loads $\geq 2 k \Omega$ and capacitive loads $\leq 100 \text{pF}$. They are internally compensated, and settle to $\pm 0.01\%$ FSR (1/2LSB) in 2.5µs.

Dual, Serial-Input,

Unipolar Configuration

Figure 9 shows DACA connected for unipolar binary operation. Similar connections apply for DACB. When V_{IN} is an AC signal, the circuit performs two-quadrant multiplication. Table 2 shows the codes for this circuit.

Bipolar Operation

Figure 10 shows the MAX532 connected for bipolar operation. The coding is offset binary, as shown in Table 3. When V_{IN} is an AC signal, the circuit performs four-quadrant multiplication. To maintain gain error specifications, resistors R1, R2, and R3 should be ratiomatched to 0.01%.

Table 2. Unipolar Code Table

DAC Latch Contents	Analog Output, V _{OUT}
MSB LSB	
1111 1111 1111	-V _{IN} x (4095/4096)
1000 0000 0000	-V _{IN} x (2048/4096) = -1/2V _{IN}
0000 0000 0001	-V _{IN} x (1/4096)
0000 0000 0000	OV

 $1LSB = V_{IN}/4096$



Figure 10. Bipolar Operation

Applications Information

Layout, Grounding, and Bypassing

For best system performance, use printed circuit boards with separate analog and digital ground planes. Wirewrap boards are not recommended. The two ground planes should be tied together at the low-impedance power-supply source, as shown in Figure 11.

The board layout should ensure that digital and analog signal lines are kept separate from each other as much as possible. Do not run analog and digital lines parallel to one another.

The output amplifiers are sensitive to high-frequency noise in the V_{DD} and V_{SS} power supplies. Bypass these supplies to the analog ground plane with $0.1\mu F$ and $10\mu F$ bypass capacitors. Minimize capacitor lead lengths for best noise rejection.

Table 3. Bipolar Code Table

DAC Latch Contents	Analog Output, V _{OUT}
MSB LSB	
1111 1111 1111	+V _{IN} x (2047/2048)
1000 0000 0001	+V _{IN} x (1/2048)
1000 0000 0000	OV
0111 1111 1111	-V _{IN} x (1/2048)
0000 0000 0000	$-V_{IN} + (2048/2048) = -V_{IN}$

 $1LSB = V_{IN}/2048$



Figure 11. Power-Supply Grounding



Figure 12. Programmable-Gain Amplifer

Programmable-Gain Amplifier (PGA)

The DAC/amplifier combination, along with access to the feedback resistors, makes the MAX532 ideal as a programmable-gain amplifier. In this application, the DAC functions as a programmable resistor in the feedback loop. This type of configuration is shown in Figure 12, and is suitable for AC gain control. The DAC code controls the gain for the PGA. As the code decreases, the effective DAC resistance increases, and so the gain also increases. The transfer function is given by:

$V_{OUT}/V_{IN} = -REQA/RFBA,$

where RFBA is the value of the feedback resistor (R/2), and REQA is the effective DAC resistance controlled by the digital input code:

$$\mathsf{REQA} = \frac{\mathsf{R}}{2} \left(\frac{4096}{\mathsf{CODE}} \right),$$

where CODE is the DAC code in decimal. The transfer function is thus:

$$\frac{V_{OUT}}{V_{IN}} = \frac{-4096}{CODE}$$

The code may be programmed between 1 and (2¹² -1). The zero code is not allowed, as it results in an openloop amplifier response.

Power-On Reset

MAX532

On power-up, the internal DAC latches are set to $00 \ldots .00.$

16 CERDIP**

±1

MAX532

MAX532BMJE

_Ordering Information (continued) ERROR PART TEMP. RANGE PIN-PACKAGE (LSBs) ±1/2 MAX532AEPE 16 Plastic DIP -40°C to +85°C MAX532BEPE -40°C to +85°C 16 Plastic DIP ± 1 MAX532AEWE -40°C to +85°C 16 Wide SO ±1/2 16 Wide SO MAX532BEWE -40°C to +85°C ± 1 MAX532AMJE 16 CERDIP** -55°C to +125°C ±1/2

**Contact factory for availability and processing to MIL-STD-883B.

-55°C to +125°C



Chip Topography

TRANSISTOR COUNT: 1324; SUBSTRATE CONNECTED TO V_{DD}.

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